

Low Capacitance Quad Array for ESD Protection

This integrated transient voltage suppressor device (TVS) is designed for applications requiring transient overvoltage protection. It is intended for use in sensitive equipment such as computers, printers, business machines, communication systems, medical equipment, and other applications. Its integrated design provides very effective and reliable protection for four separate lines using only one package. These devices are ideal for situations where board space is at a premium.

Features

- ESD Protection: IEC61000-4-2: Level 4
MILSTD 883C – Method 3015-6: Class 3
- Four Separate Unidirectional Configurations for Protection
- Low Leakage Current < 1 μ A @ 3 Volts
- Power Dissipation: 380 mW
- Small SOT-553 SMT Package
- Low Capacitance
- Complies to USB 1.1 Low Speed & High Speed Specifications
- We declare that material of product compliance with ROHS requirements.

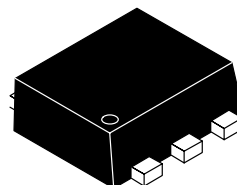
Benefits

- Provides Protection for ESD Industry Standards: IEC 61000, HBM
- Protects Four Lines Against Transient Voltage Conditions
- Minimize Power Consumption of the System
- Minimize PCB Board Space

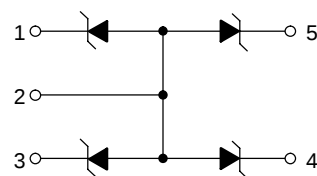
Typical Applications

- Instrumentation Equipment
- Serial and Parallel Ports
- Microprocessor Based Equipment
- Notebooks, Desktops, Servers
- Cellular and Portable Equipment

LESDA6V8AV5T1G



SOT-553



Ordering Information

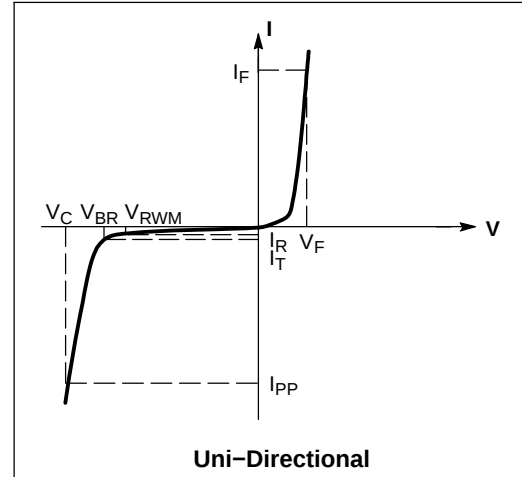
Device	Package	Shipping
LESDA6V8AV5T1G	SOT-553	3000/Tape&Reel

LESDA6V8AV5T1G

ELECTRICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
ΘV_{BR}	Maximum Temperature Coefficient of V_{BR}
I_F	Forward Current
V_F	Forward Voltage @ I_F
Z_{ZT}	Maximum Zener Impedance @ I_{ZT}
I_{ZK}	Reverse Current
Z_{ZK}	Maximum Zener Impedance @ I_{ZK}



MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Value	Unit
Peak Power Dissipation (8 X 20 μs @ $T_A = 25^\circ\text{C}$) (Note 1)	P_{PK}	20	W
Steady State Power – 1 Diode (Note 2)	P_D	380	mW
Thermal Resistance, Junction-to-Ambient Above 25°C , Derate	$R_{\theta JA}$	327 3.05	$^\circ\text{C/W}$ $\text{mW}/^\circ\text{C}$
Maximum Junction Temperature	T_{Jmax}	150	$^\circ\text{C}$
Operating Junction and Storage Temperature Range	$T_J T_{stg}$	-55 to +150	$^\circ\text{C}$
Lead Solder Temperature (10 seconds duration)	T_L	260	$^\circ\text{C}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

Device	Breakdown Voltage V_{BR} @ 1 mA (Volts)			Leakage Current I_{RM} @ V_{RM}		V_C Max @ I_{PP}		Typ Capacitance @ 0 V Bias (pF) (Note 3)		Typ Capacitance @ 3 V Bias (pF) (Note 3)	
	Min	Nom	Max	V_{RWM}	I_{RWM} (μA)	V_C (V)	I_{PP} (A)	Typ	Max	Typ	Max
LESDA6V8AV5T1G	6.47	6.8	7.14	4.3	1.0	13	1.6	12	15	6.7	9.5

- Non-repetitive current per Figure 1.
- Only 1 diode under power. For all 4 diodes under power, P_D will be 25%. Mounted on FR-4 board with min pad.
- Capacitance of one diode at $f = 1 \text{ MHz}$, $V_R = 0 \text{ V}$, $T_A = 25^\circ\text{C}$

LESDA6V8AV5T1G

TYPICAL ELECTRICAL CHARACTERISTICS

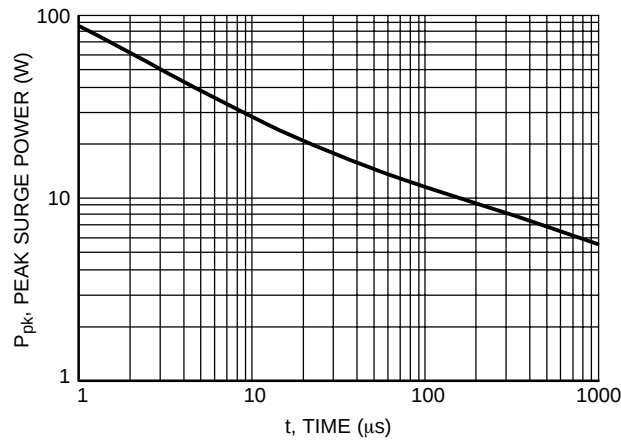


Figure 1. Pulse Width

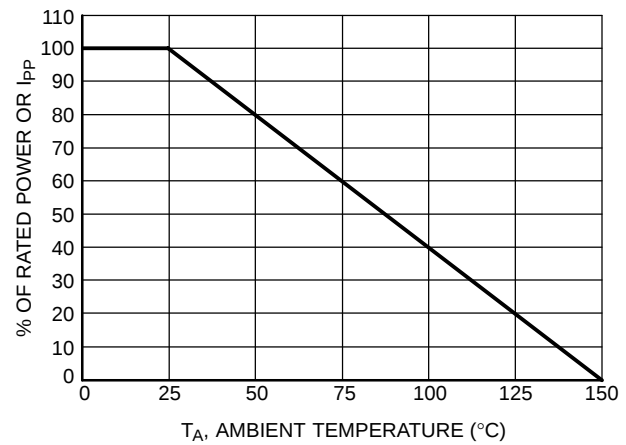


Figure 2. Power Derating Curve

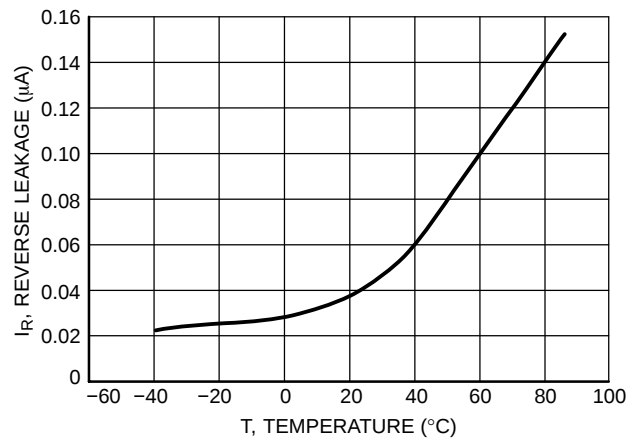


Figure 3. Reverse Leakage versus Temperature

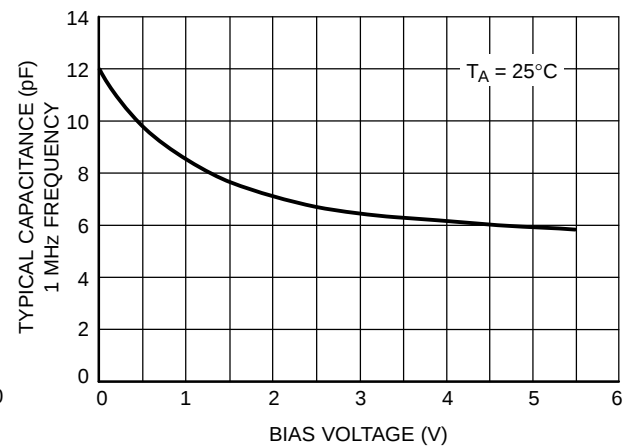


Figure 4. Capacitance

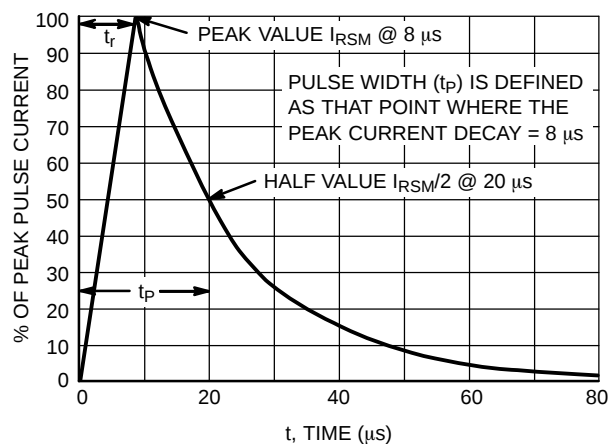


Figure 5. 8 × 20 s Pulse Waveform

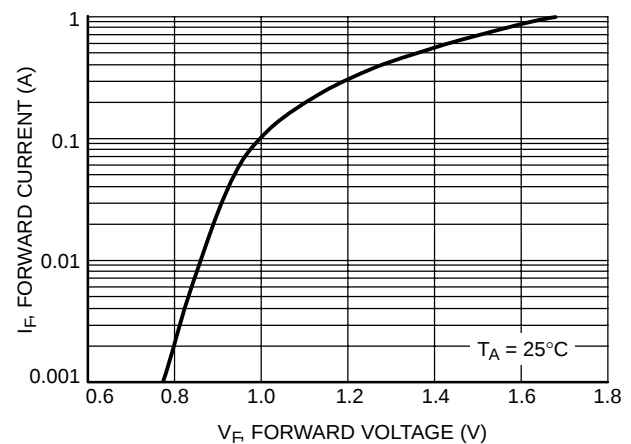
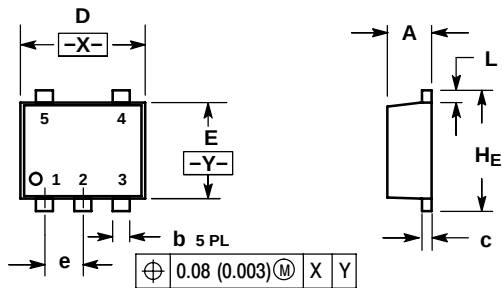


Figure 6. Forward Voltage

LESDA6V8AV5T1G

PACKAGE DIMENSIONS

SOT-553, 5 LEAD

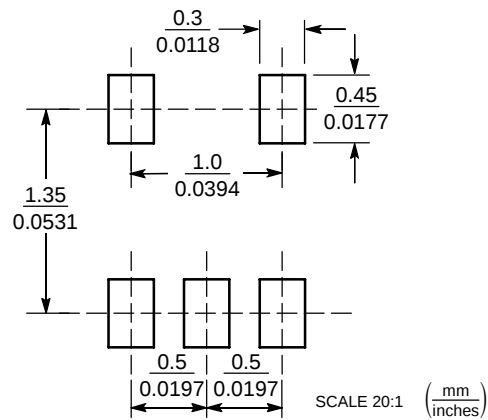


DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
c	0.08	0.13	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.063	0.067
E	1.10	1.20	1.30	0.043	0.047	0.051
e	0.50 BSC			0.020 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
H _E	1.50	1.60	1.70	0.059	0.063	0.067

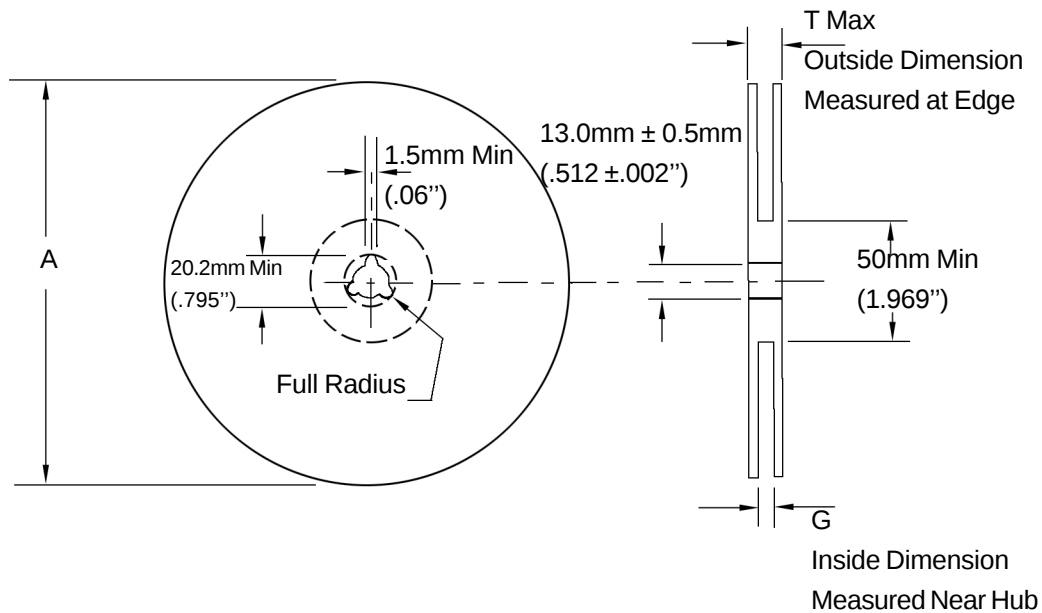
STYLE 2:

- PIN 1. CATHODE
- 2. COMMON ANODE
- 3. CATHODE 2
- 4. CATHODE 3
- 5. CATHODE 4

SOLDERING FOOTPRINT*



EMBOSSED TAPE AND REEL DATA FOR DISCRETES



Size	A Max	G	T Max
8 mm	178.0mm (7.0")	8.4mm+1.5mm, -0.0 (.33"+.039", -0.00)	10.9mm (.43")

Reel Dimensions

Metric Dimensions Govern — English are in parentheses for reference only

Storage Conditions

Temperature: 5 to 40 Deg.C (20 to 30 Deg. C is preferred)

Humidity: 30 to 80 RH (40 to 60 is preferred)

Recommended Period: One year after manufacturing

(This recommended period is for the soldering condition only. The characteristics and reliabilities of the products are not restricted to this limitation)

Shipment Specification

